


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		MDG/16/9299
1.3 Title of PCN		ST Shenzhen (China) new assembly site - TSSOP 20 products
1.4 Product Category		Products in TSSOP20 package, listed in the PCN.
1.5 Issue date		2016-06-16

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	SETTLES JEFF
2.1.2 Phone	+44 1628896222
2.1.3 Email	jeff.settles@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	To AMKOR ATP (Philippines) , ST Microcontrollers Division is adding ST Shenzhen (China) location.

4. Description of change

	Old	New
4.1 Description	Current assembly plant : AMKOR ATP (Philippines) Current Bill Of Materials : - Wire Bonding : 0.8 mil Au - Glue : 8290 Ablestik - Resin : G700K - Leadfinishing : Rough PPF	Current assembly plant, AMKOR ATP (Philippines), remains unchanged. Additional assembly plant : ST Shenzhen (China) Additional Bill Of Materials : - Wire Bonding : 0.8 mil Ag - Glue : 8601-S25 Ablestik - Resin : G700KC - Leadfinishing : PPF
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Lead color and surface finish change depending on lead finishing.	

5. Reason / motivation for change

5.1 Motivation	Today production is only issued from AMKOR ATP (Philippines). In order to ensure top class service for our customers, given the continued growth of the STM32 & STM8 families, ST Microcontrollers Division will increase production capacity and improve flexibility through the qualification of an additional assembly source.
5.2 Customer Benefit	DOUBLE SOURCING

6. Marking of parts / traceability of change

6.1 Description	Traceability of the change is ensured by ST internal tools. See more information on 9299_Aadditional information document attached.
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7. Timing / schedule

7.1 Date of qualification results	2016-09-01
7.2 Intended start of delivery	2016-10-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	PCN9299- RERMCD1512 reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-06-16

9. Attachments (additional documentations)			
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9299PpPrdtLst.pdf 9299_Additional information.pdf PCN9299- RERMCD1512 reliability plan.pdf			
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10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F030F4P6	
	STM32F031F6P6	
	STM8S003F3P6	
	STM8S003F3P6TR	
	STM8S103F2P6TR	

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